

TRADEMARK

ATTY. DOCKET NO. T-24,857 USA

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: **Kulicke & Soffa Investments, Inc.**

Serial Number: **76/328,762**

Law Office: **113**

Filed: **October 24, 2001**

Examiner: **M. Kazazian**

For: **KS (Stylized)**

Int. Classes: **7, 8, 9, 35, 37, 40
41 and 42**

CERTIFICATE OF MAILING

I hereby certify that this correspondence, along with any papers indicated as being enclosed, are being deposited as First Class Mail in an envelope addressed to: Commissioner for Trademarks, Box RESPONSE - FEE, 2900 Crystal Drive, Arlington, VA 22202-3513, on April 9, 2003.

4/9/03
Date

Arlene M. Olson
Arlene M. Olson

Commissioner for Trademarks
Box RESPONSE - FEE
2900 Crystal Drive
Arlington, VA 22202-3513

RESPONSE TO FINAL OFFICE ACTION DATED OCTOBER 10, 2002

Sir:

This communication is responsive to the Final Office Action dated October 10, 2002. Reconsideration of this application is respectfully requested in view of the following amendments and remarks.

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AMENDMENTS

1. Kindly amend the application by the addition of International Class 40.
2. Kindly amend the application to state that the date of the first use anywhere in connection with the services in International Class 40 is at least as early as March 2001, and the date of first use in commerce in connection with the services in International Class 40 is at least as early as March 2001.
3. Kindly amend the Identification of Goods and Services to read as follows:

Class 7: Dicing blades, namely, power-operated blades attached within dicing equipment to cut semiconductor wafers into individual integrated circuit chips; die attachment equipment, namely, semiconductor assembly equipment for picking up and placing individual silicon chips on a substrate and printed circuit board; solder ball placement equipment, namely semiconductor assembly equipment used to place solder balls onto substrate material; wafer bumping equipment, namely semiconductor assembly equipment for bonding stud bumps onto a silicon wafer; and wafer preparation equipment, namely, semiconductor assembly equipment for placing the wafer onto a plastic membrane and metal frame.

Class 8: Hand-operated wire bonding equipment, namely semiconductor assembly equipment for higher pitch wire bonding applications; hand-operated wire bonding tools used in the assembly of semiconductors, namely die collets, capillaries and wedge bonders.

Class 9: Computerized electrical wire bonding machine used in the assembly of semiconductors and wire bonding materials, namely, substrates with copper inlay, polymer materials, namely wire encapsulants applied over wire bonds to lock individual wires in place prior to molding, and bonding wires; bonder software, namely software used to run automated wire bonders attaching bonding wire from the integrated circuit chip to a substrate material; dicing equipment namely electrical dicing equipment for sawing integrated circuit wafers and other hard materials into usable single components; factory automation software, namely software designed for automated semiconductor material flow and gathering and collecting semiconductor assembly equipment data; wafer test products, namely, semiconductor probe cards that test the electrical functionality of

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an integrated circuit chip; package test products, namely, electrical sockets and contactors for testing the electrical functionality of a completed integrated circuit package; and electrical circuit substrates.

- Class 35: Providing on-line electronic commerce services, namely on-line catalog for selection, ordering and payment of products and services, namely, automatic wire bonding equipment, tools and materials, bonder software, die attachment equipment, dicing equipment and blades, factory automation products and services, electrical circuit substrates, manual wire bonding equipment, solder ball placement equipment, wafer bumping equipment, wafer bumping services, wafer preparation equipment, wafer test products and package test products, and on-line customer support services relating thereto, namely, on-line supply, on-line logistics and support, on-line consulting services for factory productivity consisting of monitoring semiconductor equipment status and collecting data and managing process programs in local and distant manufacturing plants to enhance overall yields and reduce cycle times.
- Class 37: Maintenance and refurbishment of equipment used in back-end assembly of semiconductors, namely, integrated circuit ball bonders, wedge bonders, manual wire bonders, automated dicing equipment, ribbon bonders, stud bumpers, wafer preparation equipment, testing equipment and ball attachment equipment; on-line consulting and advisory services for said equipment maintenance and refurbishment
- Class 40: Providing on-line information regarding packaging trends in the field of back-end assembly of semiconductors; providing technical information in the back-end assembly of semiconductors; assembly services for others, namely prototype building of mechanical components and printed circuit boards; and wafer bumping services for others, namely semiconductor assembly services for placement of solder balls onto individual integrated electrical circuits.
- Class 41: Customer training in the use of equipment for back-end assembly of semiconductors; on-line consulting and advisory services for said training.
- Class 42: Providing on-line information regarding software developments in the field of semiconductor manufacturing; providing on-line information regarding technical packaging application support, namely, design of new bonding capillaries based on customer-specific capillary configurations;

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on-line design for others in the field of semiconductor packaging assembly, namely, semiconductor packaging product design application support for the development, testing and assembly of new electrical circuits, all in the field of back-end assembly of semiconductors; providing customized on-line web pages featuring user-defined information, which includes search engines and on-line web links to other web sites; design and fabrication services for others, namely design and engineering of electrical printed circuit boards used in the semiconductor industry and the design and manufacturing of digital, analog and mix signal circuit boards; technical support services rendered in person, via telephone and via global computer network relating to the use of equipment used for the back-end assembly of semiconductors and installation of spare parts therefor.

REMARKS

Applicant submits herewith a payment of \$335 in connection with the addition of Class 40. Further, applicant submits specimens of use for goods in Classes 7 and 8 and services in Class 40. The dates of first use anywhere and first use in commerce for the specimens for each of Classes 7, 8 and 40 is at least as early as the filing date of the present application, October 24, 2001.

Applicant encloses herewith a Declaration under 37 C.F.R. Section 2.20, executed by the undersigned on behalf of applicant, verifying the dates of first use of the mark anywhere for goods in each of Classes 7 and 8 is May 2000 and for services in Class 40 is at least as early as March 2001, and the dates of first use of the mark in commerce for goods in each of Classes 7 and 8 is May 2000 and for services in Class 40 is at least as early as March 2001. The Declaration also attests that the specimens submitted herewith for the goods in each of Classes 7 and 8 and for services in Class 40 were in use anywhere and were in use in commerce at least as early as the filing date of the application, October 24, 2001.

Applicant has submitted a revised Identification of Goods and Specification of Services for the examining attorney's consideration. The examining attorney is invited to telephone the undersigned directly if further revisions are required.

Applicant submits herewith a copy of the Notice of Appeal to the Final Office Action filed with the Trademark Trial and Appeal Board on even date.

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CONCLUSION

In view of the above, it is believed that this application is in condition to be approved for registration on the Principal Register. Favorable action is, therefore, requested.

Respectfully Submitted,

Date

April 9, 2013

Bryna S. Silver

A Member of the Pennsylvania Bar

BSS/amo
Enclosures

SYNNESTVEDT & LECHNER LLP
2600 ARAMARK Tower
1101 Market Street
Philadelphia, PA 19107-2950

Telephone: (215) 923-4471
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Declaration Under 37 C.F.R. § 2.20

Mark: KS (Stylized)
Serial No.: 76/328,762.
Filed: October 24, 2001
Applicant: Kulicke & Soffa Investments, Inc.

The undersigned, Bryna S. Silver, declares:

1. That she is an attorney as defined in 37 C.F.R. § 10.1(c) who has an actual or implied written or verbal power of attorney from the Applicant, Kulicke & Soffa Investments, Inc., a Delaware corporation, and as such she is properly authorized to execute this Declaration on behalf of Kulicke & Soffa Investments, Inc.;
2. That the date of first use of the mark anywhere in connection with the goods in Class 7 is May 2000, and the date of first use in commerce of the mark in connection with the goods in Class 7 is May 2000;
3. That the specimen of use submitted herewith for International Class 7 was in use in commerce at least as early as October 24, 2001, the filing date of the application;
4. That the date of first use anywhere of the mark in connection with the goods in Class 8 is May 2000, and the date of first use in commerce of the mark in connection with the goods in Class 8 is May 2000;
5. That the specimen of use submitted herewith for International Class 8 was in use in commerce at least as early as October 24, 2001, the filing date of the application;
6. That the date of first use anywhere of the mark in connection with the services in Class 40 is at least as early as March 2001, and the date of first use in commerce of the mark in connection with the services in Class 40 is at least as early as March 2001;
7. That the specimen of use submitted herewith for International Class 40 was in use in commerce at least as early as October 24, 2001, the filing date of the application;
8. That all statements made herein of her own knowledge are true and all statements made herein on information and belief are believed to be true; that these statements are made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both (under 18 U.S.C. 1001); and that such willful false statements may jeopardize the validity of this application and any registration resulting therefrom.

KULICKE & SOFFA INVESTMENTS, INC.

Date:

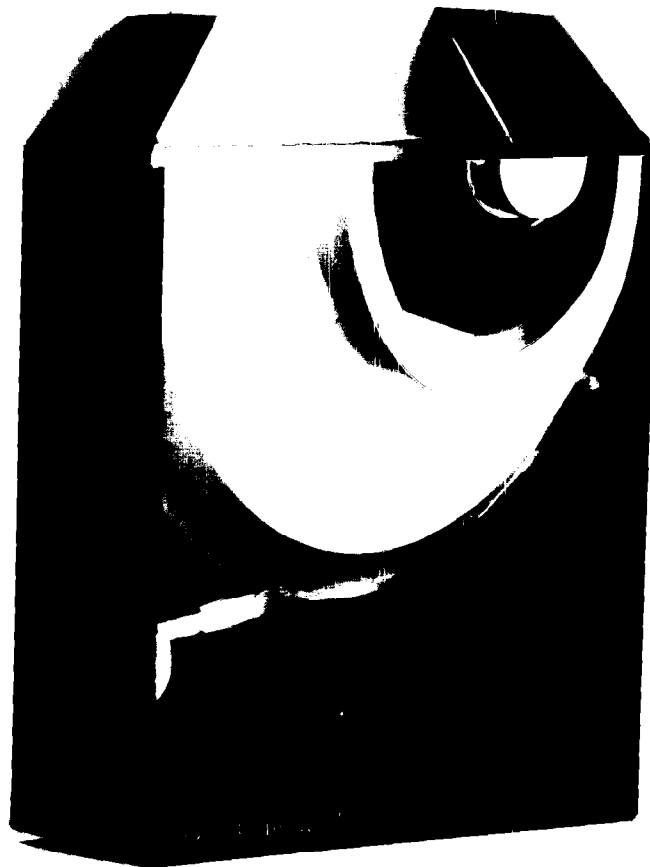
April 9, 2003

By:

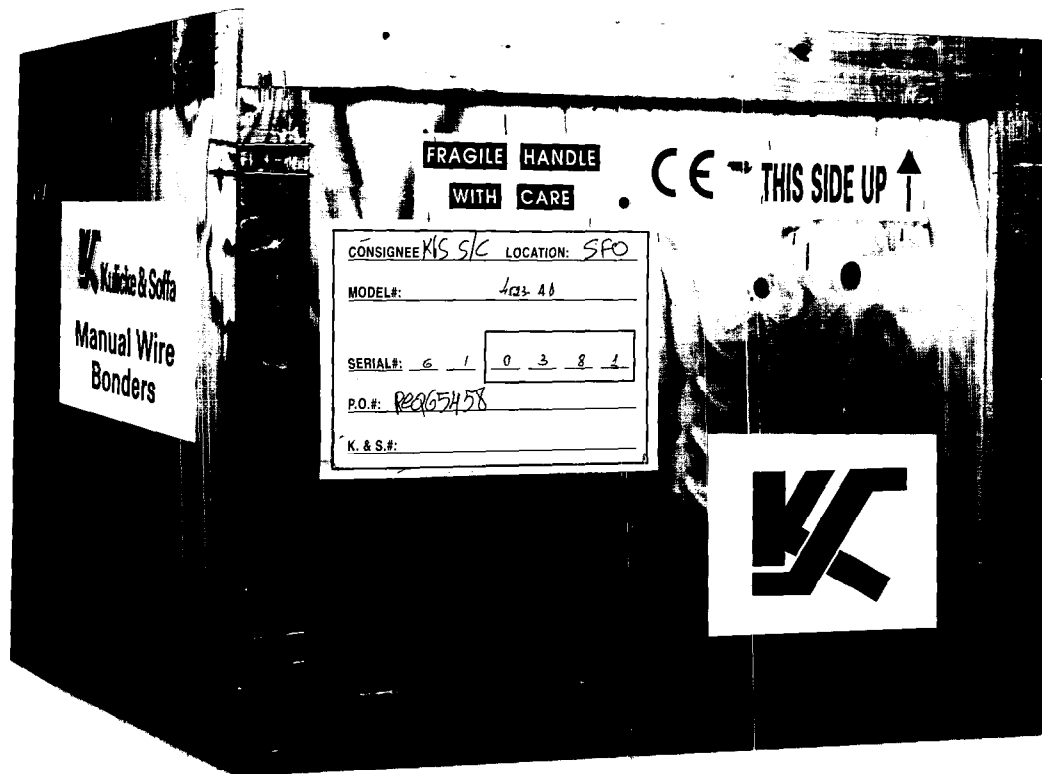
Bryna S. Silver

Bryna S. Silver
Attorney

Mark: KS (Stylized) in Class 7
Serial No.: 76/328,762
Filed: October 24, 2001
Applicant: Kulicke & Soffa Investments, Inc.



Mark: KS (Stylized) in Class 8
Serial No.: 76/328,762
Filed: October 24, 2001
Applicant: Kulicke & Soffa Investments, Inc.



Mark: KS (Stylized) in Class 40
Serial No.: 76/328,762
Filed: October 24, 2001
Applicant: Kulicke & Soffa Investments, Inc.

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
BEFORE THE TRADEMARK TRIAL AND APPEAL BOARD**

Name of Applicant: **Kulicke & Soffa Investments, Inc.**

Docket No.
T24857 USA

Serial Number of Applicant: **76/328,762**

Filing Date of Application: **October 24, 2001**

Trademark: **KS (Stylized)**

International Class(es): **007, 008, 009, 035, 037, 040, 041, 042**

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service, postage prepaid, "Express Mail Post Office to Addressee", Express Mail Label No. EV262353666US, in an envelope addressed to: BOX TTAB FEE, Commissioner for Trademarks, 2900 Crystal Drive, Arlington, Virginia 22202-3513 on Wednesday, April 9, 2003

4-9-03
Date

Mike Lavelle
Mike B. Lavelle

NOTICE OF APPEAL

Applicant hereby appeals to the Trademark Trial and Appeal Board from the decision of the Trademark Examining Attorney refusing registration in the final Office Action dated October 10, 2002.

This Appeal is taken for all classes listed above.

The total number of classes associated with this Appeal are eight (8).

The prescribed appeal fee of \$800.00 is to be paid as follows:

A check in the amount of \$800.00 is attached.

Any excess or insufficiency should be credited or debited to Deposit Account No. 19-5425.

A duplicate copy of this sheet is enclosed.

Bryna S. Silver
Signature

Dated: April 9, 2003

**Bryna S. Silver
Attorney for Applicant
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2600 Aramark Tower
1101 Market Street
Philadelphia, PA 19107-2950
(215) 923-4466**